

**In the Claims:**

This listing of claims replaces all prior versions, and listings, of claims in the application.

1. (Currently Amended) A positive photosensitive resin composition comprising: (a) 100 parts by weight of a polymer that has an alkali-soluble group, (b) 1-30 parts by weight of a compound that absorbs light with the wavelength used for exposure, but is not bleached by the exposure light, (c) 1-50 parts by weight of a quinone diazide compound, and (d) 5-500 parts by weight of particles of at least one inorganic substance selected from the group consisting of an aluminum compound, silicon compound, tin compound, titanium compound and zirconium compound with a diameter in the range of 1 nm to 30 nm.

2. (Currently Amended) A positive photosensitive resin composition comprising: (a) 100 parts by weight of a polymer that has an alkali-soluble group, (b) 1-30 parts by weight of a compound that absorbs ultraviolet light, but is not bleached by the ultraviolet light, (c) 1-50 parts by weight of a quinone diazide compound, and (d) 5-500 parts by weight of particles of at least one inorganic substance selected from the group consisting of an aluminum compound, silicon compound, tin compound, titanium compound and zirconium compound with a diameter in the range of 1 nm to 30 nm.

3. (Currently Amended) A positive photosensitive resin composition according to either Claim 1 or 2, wherein compound (b) absorbs at least one wavelength of light selected from the group of the i-line (365 nm), the h-line (405 nm) [[and] or the g-line (436 nm)].

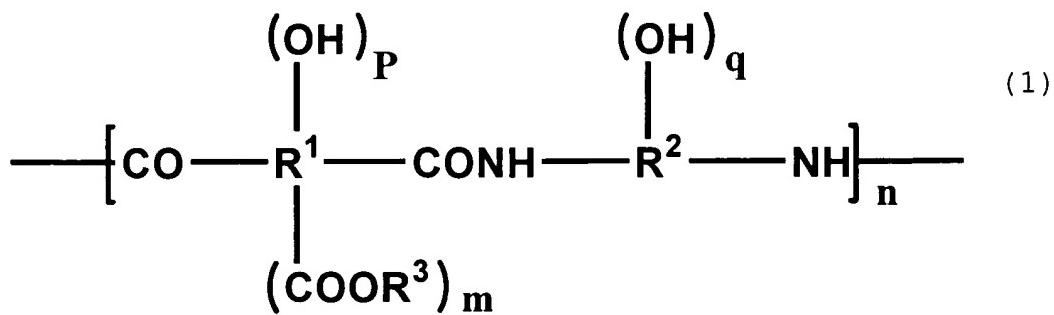
4. (Currently Amended) A positive photosensitive resin composition according to either Claim 1 or 2, wherein component (a) is novolac resin and/or resol resin.

5. (Currently Amended) A positive photosensitive resin composition according to either Claim 1 or 2, wherein component (a) is a homopolymer produced from free-radical polymerizable monomers having a phenolic hydroxyl group or a carboxyl group, or a copolymer produced from said free-radical polymerizable monomers, or a copolymer

produced through copolymerization of said free-radical polymerizable monomers having a phenolic hydroxyl group or a carboxyl group with other free-radical polymerizable monomers.

6. (Currently Amended) A positive photosensitive resin composition according to either Claim 1 or 2, wherein component (a) is a polymer that mainly comprises a structural unit as represented by general formula (1)[[.]]:

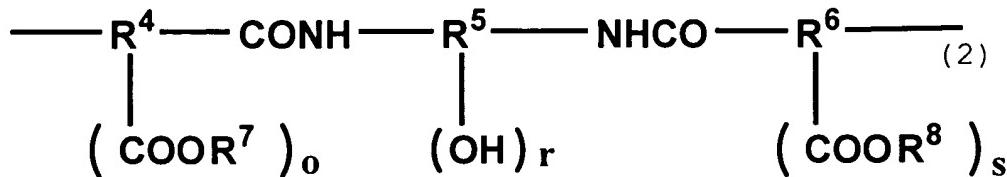
{Chemical compound 1}



In the formula, wherein R<sup>1</sup> denotes a bivalent to octavalent organic group with two or more carbon atoms, R<sup>2</sup> denotes a bivalent to hexavalent organic group with two or more carbon atoms, and R<sup>3</sup> denotes a hydrogen atom or an organic group with 1-20 carbon atoms[[. And]], n indicates an integer in the range of 10 to 100000, m an integer in the range of 0 to 2, and p and q an integer in the range of 0 to 4 that meet the following equation: p+q≥0.

7. (Currently Amended) A positive photosensitive resin composition according to either Claim 1 or 2, wherein R<sup>1</sup> (COOR<sup>3</sup>)<sub>m</sub> (OH)<sub>p</sub> in general formula (1) is represented by general formula (2)[[.]]:

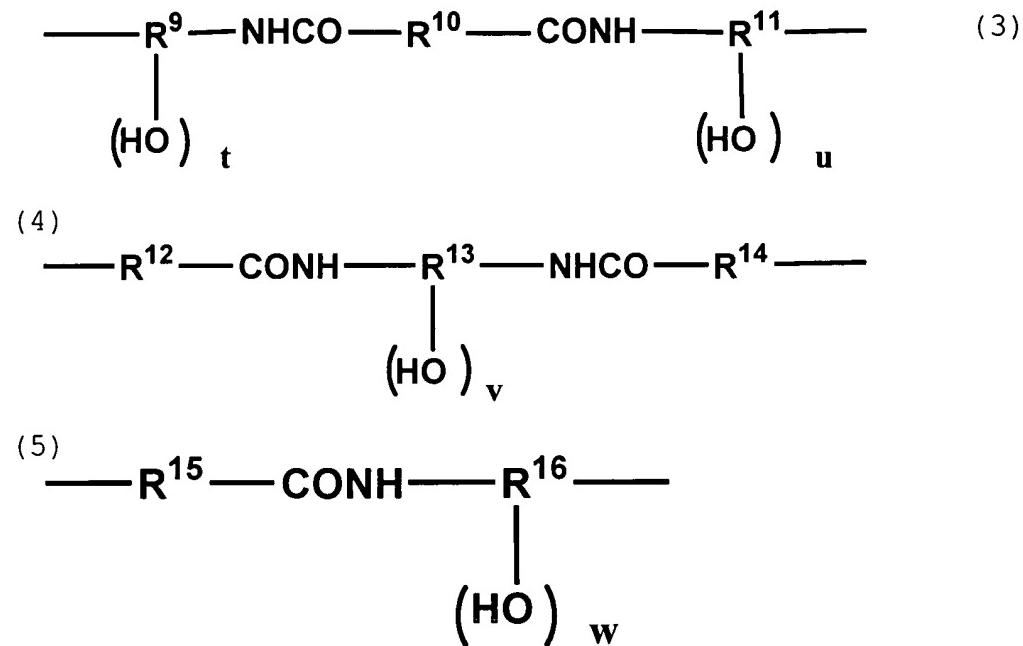
{Chemical compound 2}



wherein R<sup>4</sup> and R<sup>6</sup> represent a bivalent to quadrivalent organic group with 2-20 carbon atoms, R<sup>5</sup> represents a trivalent to hexavalent organic group with a hydroxyl group and 3-20 carbon atoms, and R<sup>7</sup> and R<sup>8</sup> represent either a hydrogen or an organic group with 1-20 carbon atoms. In addition, o and s independently denote an integer in the range of 0 to 1-20 carbon atoms. In addition, o and s independently denote an integer in the range of 0 to 2, and r shows is an integer in the range of 1 to 4.

8.. (Currently Amended) A positive photosensitive resin composition according to either Claim 1 or 2, wherein R<sup>2</sup> (OH)<sub>q</sub> in general formula (1) is at least one unit represented by any of general formulas (3)-(5)[[.]]:

{Chemical compound 3}



wherein R<sup>9</sup> and R<sup>11</sup> represent a trivalent to quadrivalent organic group that comprises a hydroxyl group and 2-20 carbon atoms, R<sup>10</sup> represents a bivalent organic group comprising 2-30 carbon atoms, [[and]] t and u being an integer of 1 or 2[[.]], R<sup>12</sup> and R<sup>14</sup> represent a bivalent organic group that comprises 2-20 carbon atoms, R<sup>13</sup> represents a trivalent to hexavalent organic group that comprises a hydroxyl group and 3-20 carbon atoms, and v an integer of 1-4[[.]], R<sup>15</sup> represents a bivalent organic group that comprises 2-20 carbon atoms, R<sup>16</sup> represents a trivalent

to hexavalent organic group that comprises a hydroxyl group and 3-20 carbon atoms, and w an integer of 1-4.

9. (Currently Amended) A positive photosensitive resin composition according to ~~either~~ Claim 1 or 2, wherein absorption at wavelengths of 400 to 700 nm originating in the compound used as component (b) does not increase during heating at 130 to 400°C.

10. (Currently Amended) A positive photosensitive resin composition according to ~~either~~ Claim 1 or 2, wherein component (b) comprises one or more compounds selected from the group consisting of coumarin derivatives, benzotriazole derivatives and hydroxylbenzophenone derivatives.

11. (Currently Amended) A positive photosensitive resin composition according to ~~either~~ Claim 1 or 2, wherein the transmittance of photosensitive resin composition film at 365 to 436 nm is in the range of 20-70% per 1.2  $\mu\text{m}$ .

12. (Currently Amended) A relief pattern of photosensitive resin produced by exposing a positive photosensitive resin composition according to ~~any of Claims 1-11~~ Claim 1 or 2 to ultraviolet light and subsequently heating it.

13. (Original) A relief pattern of heat resistant resin comprising dots with a size of 1  $\mu\text{m}$  to 10  $\mu\text{m}$  arranged grid-like at intervals of 0.1  $\mu\text{m}$  to 1.0  $\mu\text{m}$ , wherein each dot has a light transmittance at 400 nm of 80% or more per  $\mu\text{m}$  and a taper angle of 55° or less.

14. (Original) A solid-state image sensor produced from a relief pattern of photosensitive resin according to Claim 12.

15. (Original) A solid-state image sensor produced from a relief pattern of heat-resistant resin according to Claim 13.